



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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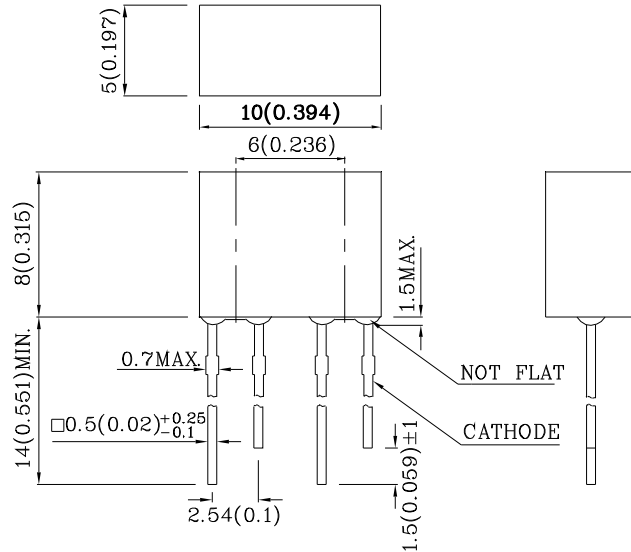


**Features**

- Robust package
- Uniform light disbursement
- Ideal for backlighting logos or icons
- Excellent for flush mounting
- RoHS compliant



**Package Schematics**



**Notes:**

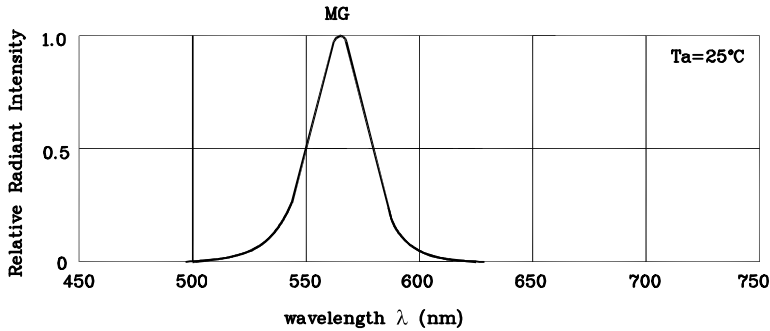
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.
3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T <sub>A</sub> =25°C)		MG (GaP)	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	140	mA
Power Dissipation	P <sub>D</sub>	62.5	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

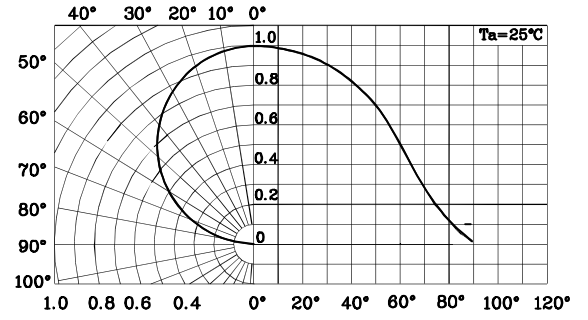
Operating Characteristics (T <sub>A</sub> =25°C)		MG (GaP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =20mA)	V <sub>F</sub>	2.2	V
Forward Voltage (Max.) (I <sub>F</sub> =20mA)	V <sub>F</sub>	2.5	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	I <sub>R</sub>	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I <sub>F</sub> =20mA)	λ <sub>P</sub>	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I <sub>F</sub> =20mA)	λ <sub>D</sub>	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =20mA)	Δλ	30	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	C	15	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I <sub>F</sub> =20mA) mcd		Wavelength CIE127-2007* nm λ <sub>P</sub>	Viewing Angle 2θ 1/2
				min.	typ.		
XEMG22D	Green	GaP	Green Diffused	6*	11*	565*	120°

\*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

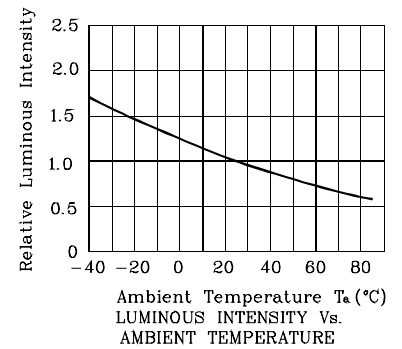
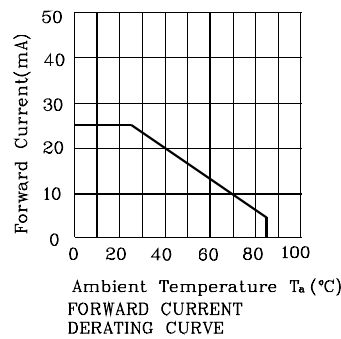
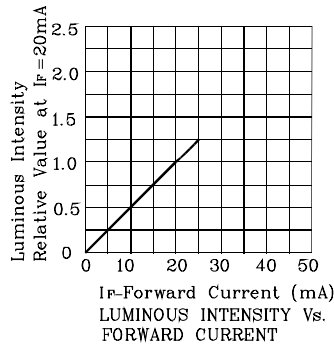
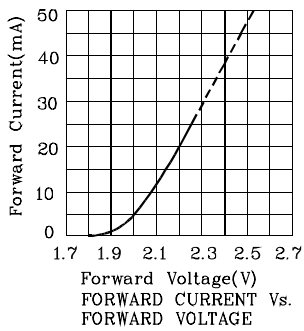


RELATIVE INTENSITY Vs. CIE WAVELENGTH

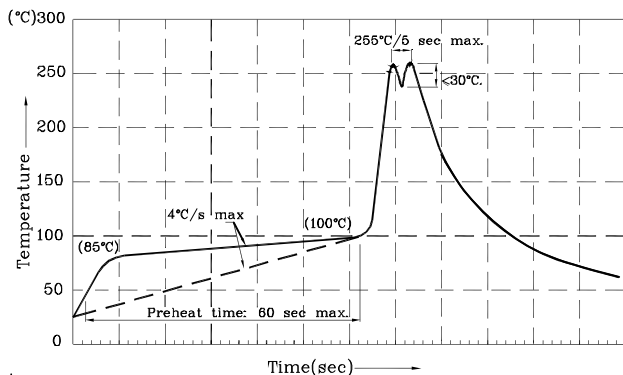


SPATIAL DISTRIBUTION

❖ MG



Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes:

1. Recommend pre-heat temperature of  $105^\circ\text{C}$  or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of  $260^\circ\text{C}$
2. Peak wave soldering temperature between  $245^\circ\text{C} \sim 255^\circ\text{C}$  for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above  $85^\circ\text{C}$ .
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.

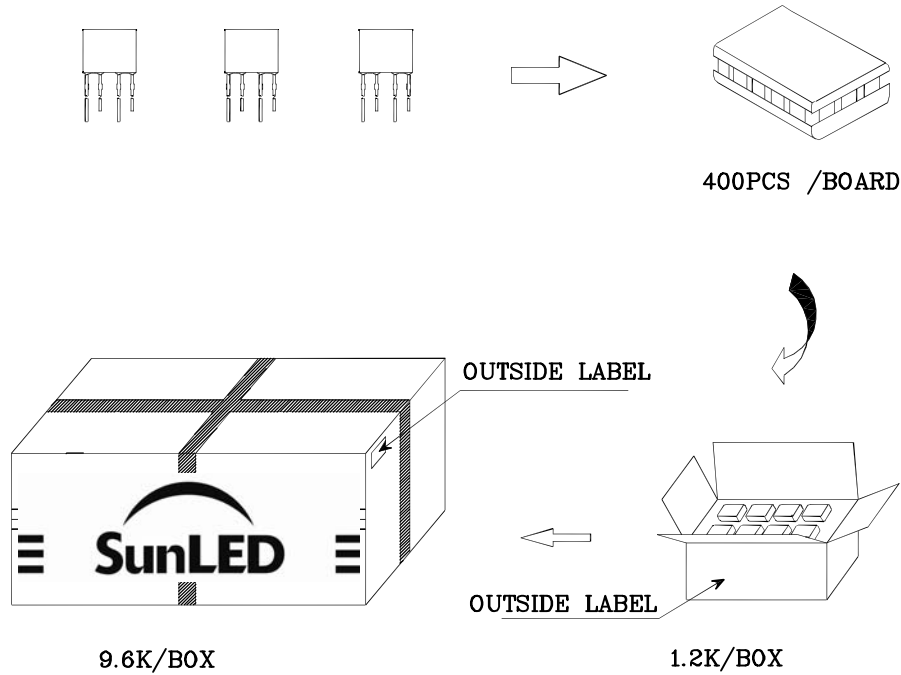
Remarks:


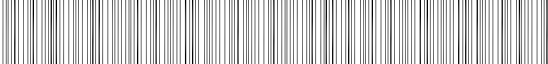
If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength:  $\pm 1\text{nm}$
2. Luminous Intensity / Luminous Flux:  $\pm 15\%$
3. Forward Voltage:  $\pm 0.1\text{V}$

Note: Accuracy may depend on the sorting parameters.

**PACKING & LABEL SPECIFICATIONS**



		<table border="1"> <tr> <td>Q.C.</td> <td>Q C</td> </tr> <tr> <td>XX</td> <td>XX XXXX</td> </tr> <tr> <td colspan="2" style="text-align: center;">PASSED</td> </tr> </table>	Q.C.	Q C	XX	XX XXXX	PASSED	
Q.C.	Q C							
XX	XX XXXX							
PASSED								
P/NO : XE <sub>xx</sub> 22 <sub>x</sub>								
QTY : 400 pcs		CODE: XXX						
S/N : XX								
LOT NO:								
 xxxxxxxxxxxxxxxxxxxxxxxxxxxx								
RoHS Compliant								

**TERMS OF USE**

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2. Contents within this document are subject to improvement and enhancement changes without notice.
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4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
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